

# **Advanced Metallization And Interconnect Systems For ULSI Applications In 1995 By Russell & Shi-Qing Wang (eds.) Ellwanger**

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## **Patent us5674787 - selective electroless copper**

Patent US5674787 - Selective electroless copper deposited

Domain: [www.google.pl](http://www.google.pl) File: [/patents/US5674787](http://patents/US5674787)

## **Call for papers now open for 2009 advanced**

Call for Papers Now Open for 2009 Advanced Metallization deposition processes in advanced metallization, novel interconnect systems concepts such as

Domain: [www.nanotech-now.com](http://www.nanotech-now.com) File: [/news.cgi?story\\_id=33461](http://news.cgi?story_id=33461)

## **Lowering of intralevel capacitance using air gap**

Venue: Proc. Advanced Metallization and Interconnect Systems for ULSI Applications

Domain: [citeseerx.ist.psu.edu](http://citeseerx.ist.psu.edu) File: [/showciting?cid=8471946](http://showciting?cid=8471946)

## **Method for low temperature annealing of**

especially those used for advanced interconnect size and the as the interconnect metallization by using a damascene and

Domain: [www.docstoc.com](http://www.docstoc.com) File: [/docs/57255245/Method-For-Low-Temperature-Annealing-Of-Metallization-Micro-structures-In-The-Production-Of-A-Microelectronic-Device---Patent-7462269](http://docs/57255245/Method-For-Low-Temperature-Annealing-Of-Metallization-Micro-structures-In-The-Production-Of-A-Microelectronic-Device---Patent-7462269)

## **Advanced metallization conference (amc) - home**

This conference is devoted to leading-edge research in the field of advanced metallization and 3-D the-art and future directions in interconnect systems.

Domain: [www.advancedmetallizationconference.com](http://www.advancedmetallizationconference.com) File: [/](http://)

## **Ieee international interconnect technology**

IEEE International Interconnect Technology Conference/ Advanced will be held in conjunction with the Advanced Metallization and interconnect systems.

Domain: [ieee-region6.org](http://ieee-region6.org) File: [/2014/ieee-international-interconnect-technology-conference-advanced-metallization-conference/](http://2014/ieee-international-interconnect-technology-conference-advanced-metallization-conference/)

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### **Thermal ald of cu via reduction of cuxo**

Thermal ALD of Cu via reduction of CuxO films for the advanced metallization in spintronic and ULSI interconnect systems Autorzy.

Domain: yadda.icm.edu.pl File: /yadda/element/bwmeta1.element.ieee-000006068736

### **Patent us7244677 - method for filling recessed**

A method for filling recessed micro-structures at a surface of a semiconductor wafer with metallization is set forth. In accordance with the method, a metal layer is

Domain: www.google.co.in File: /patents/US7244677

### **Library genesis 339000 - 339999 ::**

Library Genesis 339000 - 339999. Advanced Metallization for Ulsi Applications Advanced Metallization and Interconnect Systems for Ulsi Applications in

Domain: booktracker.org File: /viewtopic.php?t=15809

### **Preview: conference looks beyond 32-nm to 3-d | ee**

The 2011 Advanced Metallization Conference will be devoted to leading-edge research in the field of advanced metallization and 3-D integration for ULSI IC applications.

Domain: www.eetimes.com File: /author.asp?section\_id=36&doc\_id=1266008

### **Event details: materials for advanced**

Materials for advanced metallization. novelties in alternative interconnect systems and more widely advanced materials and structures \* Cu interconnect

Domain: nanotechweb.org File: /cws/event/13756

### **Thermal stability of ultra-thin cosi2 films on**

the thermal stability of ultra-thin in: R.C. Ellwanger and Shi-Qing Wang (Eds.), Advanced Metallization and Interconnect Systems for ULSI Applications

Domain: www.sciencedirect.com File: /science/article/pii/S0169433297800931

### **Ieee xplore abstract - advanced interconnect**

Advanced interconnect systems for ULSI advanced interconnect systems of low-k dielectric and dual damascene architecture for both Al and Cu metallization

Domain: ieeexplore.ieee.org File: /xpls/abs\_all.jsp?arnumber=785782&isnumber=17030

### **Cinii books - wang, shi- qing**

Advanced metallization and interconnect systems for ULSI applications in 1995 : Russell C. Ellwanger, Shi-Qing Wang.

Domain: ci.nii.ac.jp File: /author/DA11347316

### **Uncategorized | lumbungbuku's blog | page 109**

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### **Advanced metallization and interconnect systems**

Advanced Metallization and Interconnect Systems for ULSI Applications in 1996. Volume 12

Domain: www.cambridge.org File: /us/academic/subjects/engineering/materials-science/advanced-metallization-and-interconnect-systems-ulsi-applications-1996-volume-12

### **Advanced metallization and interconnect systems**

Advanced Metallization and Interconnect Systems for ULSI Applications in 1997: Volume 13 (MRS Conference Proceedings) [Robin Cheung, Jeffrey Klein, Kazuo Tsubouchi

Domain: [www.amazon.com](http://www.amazon.com) File: /Advanced-Metallization-Interconnect-Systems-Applications/dp/1558994122

### **Method for fabrication of a semiconductor device**

A method for fabricating a device, the method including: providing a first layer including first transistors, where the first transistors include a mono-crystalline

Domain: [www.google.co.in](http://www.google.co.in) File: /patents/US8703597

### **Advanced metallization and interconnect systems**

Advanced Metallization and Interconnect Systems for ULSI Applications Advanced Metallization and Interconnect Russell C.; Ellwanger, R. C.; Wang, Shi-Qing.

Domain: [www.buecher.de](http://www.buecher.de) File: /shop/englische-buecher/advanced-metallization-and-interconnect-systems-for-ulsi-applications-in-1995-volume-11/gebundenes/products\_products/detail/prod\_id/35490185/

### **Patent us7144805 - method of submicron**

Methods for depositing a metal into a micro-recessed structure in the surface of a microelectronic workpiece are disclosed. The methods are suitable for use in

Domain: [www.google.com](http://www.google.com) File: /patents/US7144805

### **Selective electroless copper deposited**

A method or utilizing electroless copper deposition to selectively form encapsulated copper plugs to connect conductive regions on a semiconductor. A via opening in

Domain: [www.google.co.in](http://www.google.co.in) File: /patents/US5674787

### **Cinii - advanced metallization and**

Advanced metallization and interconnect systems for ULSI applications in Advanced metallization and interconnect systems for Russell C. Ellwanger, Shi-Qing Wang

Domain: [ci.nii.ac.jp](http://ci.nii.ac.jp) File: /ncid/BA35820037

### **Advanced metallization conference 2003 amc 2003**

Cambridge University Press Advanced Metallization Conference 2003 Gary W. Ray, Novellus Systems , Inc., San Jose; Tom S. Smy, Carleton University,

Domain: [www.cambridge.org](http://www.cambridge.org) File: /us/academic/subjects/engineering/materials-science/advanced-metallization-conference-2003-amc-2003-volume-19

### **Patent us6806186 - submicron metallization using**

Methods for depositing a metal into a micro-recessed structure in the surface of a microelectronic workpiece are disclosed. The methods are suitable for use in

Domain: [www.google.com](http://www.google.com) File: /patents/US6806186

### **Metallization - ieee conferences, publications,**

2010 Materials for Advanced Metallization novelties in alternative interconnect systems and more widely advanced materials and structures relevant to micro and

Domain: [technav.ieee.org](http://technav.ieee.org) File: /tag/7285/metallization

### **Reliability of advanced metallization systems**

Reliability of advanced metallization systems. Rosa Leon, Jet Propulsion Laboratory March 2003. Brief description of advanced interconnect technology .

Domain: [nepp.nasa.gov](http://nepp.nasa.gov) File: /DocUploads/A3BBBDA7-73F0-47D3-96649DE90D64A5C4/technology%20readiness%20overview%20metallization%20revised.doc

**Patent us5695810 - use of cobalt tungsten**

A technique for electrolessly depositing a CoWP barrier material on to copper and electrolessly depositing copper onto a CoWP barrier material to prevent copper

**Catalog record: advanced metallization conference**

Advanced Metallization Advanced metallization and interconnect systems for Asian Regional Conference on the Evolution of the System of

Domain: catalog.hathitrust.org File: /Record/005070787

**Www.google.com**

www.google.com

Domain: www.google.com File: /patents/US8836073

**Sub-half micron metallization using high-pressure**

Sub-half micron metallization using high Plugs, Advanced Metallization and Interconnect Systems for Advanced Metallization and Interconnect Systems

Domain: www.sciencedirect.com File: /science/article/pii/S0167931797001263

**Temperature dependence of decomposition pathway of**

The decomposition of dimethylaluminum hydride of Advanced Metallization and Interconnect of Advanced Metallization and Interconnect Systems for

Domain: www.sciencedirect.com File: /science/article/pii/S0022024897003904

**Patent us7001471 - method and apparatus for**

A method for filling recessed microstructures at a surface of a microelectronic workpiece, such as a semiconductor wafer, with metallization is set forth. In

Domain: www.google.co.in File: /patents/US7001471

**Ultrathin diffusion barriers/liners for gigascale**

Advanced Metallization and Interconnect Systems for ULSI Applications in 1996, Advanced Metallization and Interconnect Systems for ULSI Applications in 1995,

Domain: www.annualreviews.org File: /doi/full/10.1146/annurev.matsci.30.1.363

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**Low dielectric constant materials for advanced**

S. Jeng et al., Advanced Metallization and Interconnect Systems for ULSI Applications in 1995, Low dielectric constant materials for advanced interconnects Journal

Domain: link.springer.com File: /article/10.1007%2Fs11837-999-0158-8

**Patent us5942799 - multilayer diffusion barriers -**

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Advanced metallization and interconnect systems for ULSI applications [Russell C Ellwanger; Shi-Qing Wang; > # Advanced metallization and interconnect

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**Patent us6565729 - method for electrochemically**

Patent US6565729 - Method for electrochemically depositing

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